

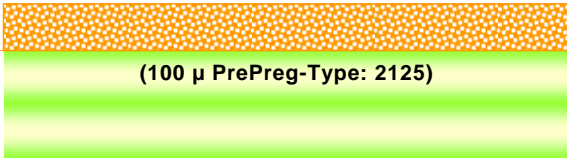
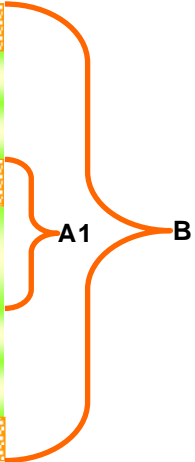
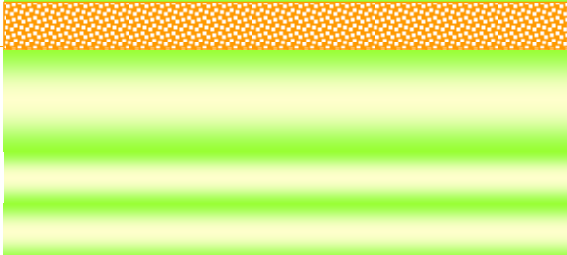

**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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**03 100 FR4 55 L46.35 P10 s1**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**03\_100\_FR4\_55\_L46.35\_p10\_s1**

Layers	in $\mu$	Material	Build-Up	Assembly
<b>Layer-1</b>	55 $\mu$	Copper		
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
<b>Layer-2</b>	35 $\mu$	Copper		
	460 $\mu$	L-FR4		
	100 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
<b>Layer-99</b>	55 $\mu$	Copper		

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